

The SC-1 from Swiss Cluster represents the next generation in materials fabrication, being the first to combine Atomic Layer Deposition (ALD) and Physical Vapour Deposition (PVD) in a compact and modular equipment.

This patent-pending innovative vertical chamber arrangement forgoes the need for transfer arms and antechambers, avoiding the pitfalls that make the traditional cluster equipment having a large footprint with high acquisition and operating costs.

The chambers are divided by a gate valve that is closed when performing ALD and opens to perform a PVD process without the need to move the substrate or ever breaking vacuum.

The SC-1 can fabricate n number of multinanolayers of multiple material systems from the PVD and ALD/CVD materials library. Both hardware and software are designed to be completely modular, making it easy to configure, service, and upgrade.

All these features combined with our flexible machine control and recipe creation software suite gives you complete control over the system and its automation.

The SC-1 is a materials factory exploiting the benefits of both ALD and PVD.

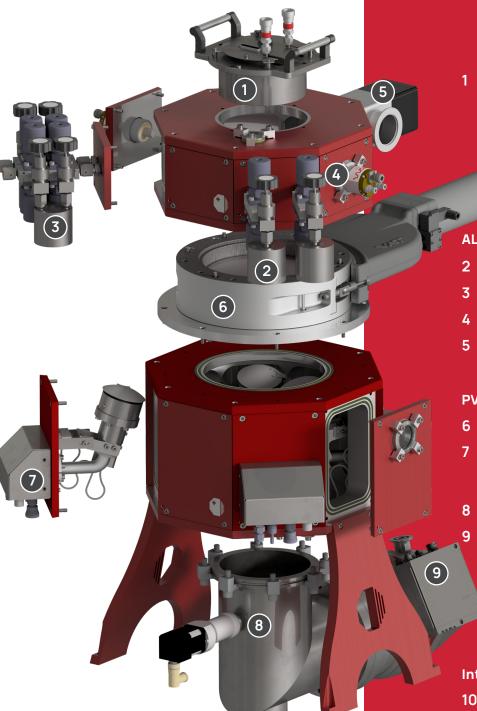
# Technical Specifications

Substrate Holders Temperature Gradient Stage (30°C to Sizes and Temperatures High Temperature (max. 900°C) Rotational and z-stages with bias  Loading Loading from the top via interchangeable substrate holders Custom-made frame holders for 3D parts Cleanroom and Glovebox compatible  ALD Precursors
substrate holders Custom-made frame holders for 3D parts Cleanroom and Glovebox compatible  ALD Up to 500°C
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Precursors  Up to 8 gas sources with 6 individual inlets Ozone option Microwave plasma sources for PE-ALD
PVD 1 to 4 inch targets Sputtering Different power supplies: DC, RF, HiPIMS Sources
Standard Single layers and multinanolayers of:  Materials Al <sub>2</sub> O <sub>3</sub> , ZnO, SiO <sub>2</sub> , TiO <sub>2</sub> , Y <sub>2</sub> O <sub>3</sub> , ZrO <sub>2</sub> , HfO <sub>2</sub> , Cu,  Al, Ti, Mg, Nb, Li, and more





## **SC-1 Series**



(10)

Substrate Holders

Temperature Gradient Stage High Temperature Rotational Stage

#### **ALD Chamber**

- 2 Single Heated/Unheated Lines
- 3 Bubbler Heated Lines
- 4 MW Plasma Option (PE-ALD)
- 5 Exhaust Lines
  Exposure and Butterfly Valves
  Dry Vacuum Pump

#### **PVD Chamber**

- 6 Gate Valve
- 7 Sputtering Sources 1 to 4 inch targets DC, RF, HiPIMS
- 8 Motorized Throttle Valve
- 9 Turbomolecular Pump

### **Integrated In Situ Tools**

- 10 Stress Measurements
- + OES
  Tof-MS
  Ellipsometer

#### **Swiss Cluster AG**

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